L Number	Hits	Search Text	DB	Time stamp
1	373	glass adj1 (substrate or board) and (vias or (through adj1	USPAT;	2004/07/14 14:47
'	3.5	holes)) and (filler or sealant)	US-PGPUB	
		,	EPO;	
			DERWENT;	
			IBM_TDB	
3	29	361/760 and (glass adj1 (substrate or board)) and (vias or	USPAT;	2004/07/14 14:48
		(through adj1 holes))	US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
4	16	361/748 and (glass adj1 (substrate or board)) and (vias or	USPAT;	2004/07/14 14:49
		(through adj1 holes))	US-PGPUB;	
			EPO;	
Ì			DERWENT;	
5	1.4	361/736 and (gloss adid (substrate or board)) and (vice or	IBM_TDB	2004/07/14 14:40
3	14	361/736 and (glass adj1 (substrate or board)) and (vias or (through adj1 holes))	USPAT; US-PGPUB;	2004/07/14 14:49
		(tillough auji holes))	EPO:	
			DERWENT;	
·			IBM_TDB	
6	10	361/750 and (glass adj1 (substrate or board)) and (vias or	USPAT;	2004/07/14 14:49
		(through adj1 holes))	US-PGPUB	
		,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	EPO,	
	i		DERWENT;	
			IBM_TDB	
7	9	361/751 and (glass adj1 (substrate or board)) and (vias or	USPAT;	2004/07/14 14:49
		(through adj1 holes))	US-PGPUB;	
			EPO;	
			DERWENT;	
8	11	361/761 and (gloss adid (substrate or heard)) and (vice are	IBM_TDB	2004/07/44 44:40
°	1.1	361/761 and (glass adj1 (substrate or board)) and (vias or (through adj1 holes))	USPAT; US-PGPUB;	2004/07/14 14:49
		(tillough auj Fholes))	EPO;	
			DERWENT:	
	-		IBM_TDB	
9	3	361/765 and (glass adj1 (substrate or board)) and (vias or	USPAT;	2004/07/14 14:49
		(through adj1 holes))	US-PGPUB;	
			EPO;	
			DERWENT;	
10	40	264/767 and /plans adid /autistants and 100 170	IBM_TDB	0004/07/44 44 45
10	13	1	USPAT;	2004/07/14 14:49
		(through adj1 holes))	US-PGPUB; EPO;	•
]			DERWENT;	
			IBM_TDB	
11	2	361/768 and (glass adj1 (substrate or board)) and (vias or	USPAT;	2004/07/14 14:50
1	_	(through adj1 holes))	US-PGPUB	
1			EPO;	
			DERWENT;	
		<u></u>	IBM_TDB	
12	14	174/250 and (glass adj1 (substrate or board)) and (vias or	USPAT;	2004/07/14 14:50
1		(through adj1 holes))	US-PGPUB;	
1			EPO;	
1			DERWENT;	
13	22	174/255 and (glass adj1 (substrate or board)) and (vias or	IBM_TDB USPAT;	2004/07/14 14:51
'`	44	(through adj1 holes))	US-PGPUB;	2007/01/14 14.01
		( 1.g., daj i 110.00//	EPO;	•
			DERWENT;	
			IBM_TDB	

14	26	174/262 and (glass adj1 (substrate or board)) and (vias or	USPAT;	2004/07/14 14:51
1		(through adj1 holes))	US-PGPUB;	
			EPO;	ļ
			DERWENT;	
			IBM_TDB	
15	12	174/263 and (glass adj1 (substrate or board)) and (vias or	USPAT;	2004/07/14 14:51
		(through adj1 holes))	US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
16	31	174/260 and (glass adj1 (substrate or board)) and (vias or	USPAT;	2004/07/14 14:51
	1	(through adj1 holes))	US-PGPUB;	
			EPO;	
		· ·	DERWENT;	
			IBM_TDB	
2	48	(glass adj1 (substrate or board)) and (vias or (through near	USPAT;	2004/07/14 14:51
!		holes)) and filler and (display adj1 device)	US-PGPUB;	
			EPO;	
			DERWENT;	
L			IBM_TDB	